

FDPF390N15A

N-Channel PowerTrench® MOSFET

150 V, 15 A, 40 mΩ

Features

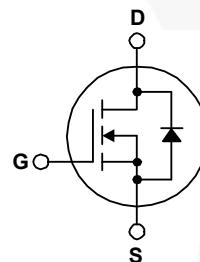
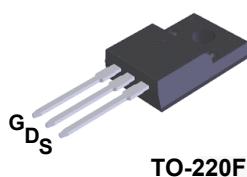
- $R_{DS(on)} = 31 \text{ m}\Omega$ (Typ.) @ $V_{GS} = 10 \text{ V}$, $I_D = 15 \text{ A}$
- Fast Switching Speed
- Low Gate Charge, $Q_G = 14.3 \text{ nC}$ (Typ.)
- High Performance Trench Technology for Extremely Low $R_{DS(on)}$
- High Power and Current Handling Capability
- RoHS Compliant

Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

Applications

- Consumer Appliances
- LED TV
- Synchronous Rectification
- Uninterruptible Power Supply
- Motor Solar Inverter



Absolute Maximum Ratings

$T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter		FDPF390N15A	Unit
V_{DSS}	Drain to Source Voltage		150	V
V_{GSS}	Gate to Source Voltage		± 20	V
I_D	Drain Current	- Continuous ($T_C = 25^\circ\text{C}$, Silicon Limited)	15	A
		- Continuous ($T_C = 100^\circ\text{C}$, Silicon Limited)	10	
I_{DM}	Drain Current	- Pulsed	(Note 1)	A
E_{AS}	Single Pulsed Avalanche Energy		78	mJ
dv/dt	Peak Diode Recovery dv/dt		(Note 3)	V/ns
P_D	Power Dissipation	($T_C = 25^\circ\text{C}$)	22	W
		- Derate above 25°C	0.18	
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +175	°C
T_L	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds.		300	°C

Thermal Characteristics

Symbol	Parameter	FDPF390N15A	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	5.7	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FDPF390N15A	FDPF390N15A	TO-220F	Tube	N/A	N/A	50 units

Electrical Characteristics

$T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
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Off Characteristics

BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu\text{A}, V_{GS} = 0 \text{ V}$	150	-	-	V
$\Delta \text{BV}_{\text{DSS}} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$, Referenced to 25°C	-	0.1	-	$^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 120 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	1	μA
		$V_{DS} = 120 \text{ V}, T_C = 125^\circ\text{C}$	-	-	500	
I_{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	± 100	nA

On Characteristics

$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu\text{A}$	2.0	-	4.0	V
$R_{DS(\text{on})}$	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 15 \text{ A}$	-	31	40	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{DS} = 10 \text{ V}, I_D = 15 \text{ A}$	-	32	-	S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 75 \text{ V}, V_{GS} = 0 \text{ V}$	-	965	1285	pF
C_{oss}	Output Capacitance	$f = 1 \text{ MHz}$	-	96	130	pF
C_{rss}	Reverse Transfer Capacitance		-	5.8	-	pF
$C_{oss(er)}$	Energy Related Output Capacitance	$V_{DS} = 75 \text{ V}, V_{GS} = 0 \text{ V}$		169	-	pF
$Q_{g(\text{tot})}$	Total Gate Charge at 10V		-	14.3	18.6	nC
Q_{gs}	Gate to Source Gate Charge	$V_{DS} = 75 \text{ V}, I_D = 27 \text{ A}$		5.0	-	nC
Q_{gs2}	Gate Charge Threshold to Plateau	$V_{GS} = 10 \text{ V}$		-	2.0	nC
Q_{gd}	Gate to Drain "Miller" Charge		(Note 4)	-	3.5	nC
ESR	Equivalent Series Resistance (G-S)	$f = 1 \text{ MHz}$	-	1.4	-	Ω

Switching Characteristics

$t_{d(\text{on})}$	Turn-On Delay Time	$V_{DD} = 75 \text{ V}, I_D = 27 \text{ A}$	-	14	38	ns	
t_r	Turn-On Rise Time	$V_{GS} = 10 \text{ V}, R_G = 4.7 \Omega$	-	10	30	ns	
$t_{d(\text{off})}$	Turn-Off Delay Time		-	20	50	ns	
t_f	Turn-Off Fall Time		(Note 4)	-	5	20	ns

Drain-Source Diode Characteristics

I_S	Maximum Continuous Drain to Source Diode Forward Current	-	-	15	A	
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	64	A	
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{SD} = 15 \text{ A}$	-	-	1.25	V
t_{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{SD} = 27 \text{ A}$	-	63	-	ns
Q_{rr}	Reverse Recovery Charge	$dI_F/dt = 100 \text{ A}/\mu\text{s}$	-	131	-	nC

Notes:

1. Repetitive rating: pulse-width limited by maximum junction temperature.
2. Starting $T_J = 25^\circ\text{C}$, $L = 3 \text{ mH}$, $I_{SD} = 7.2 \text{ A}$
3. $I_{SD} \leq 15 \text{ A}$, $di/dt \leq 200 \text{ A}/\mu\text{s}$, $V_{DD} \leq \text{BV}_{\text{DSS}}$, starting $T_J = 25^\circ\text{C}$
4. Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

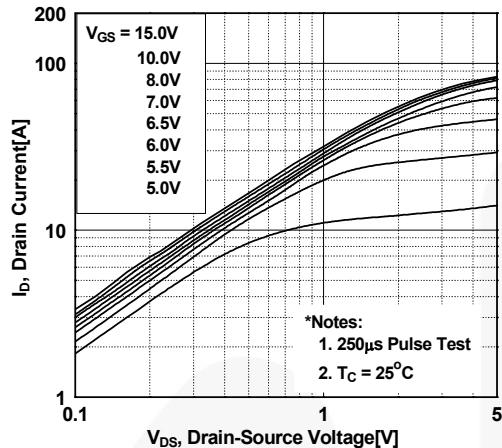


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

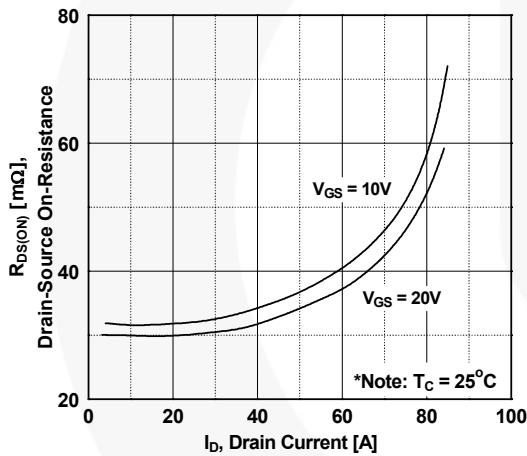


Figure 5. Capacitance Characteristics

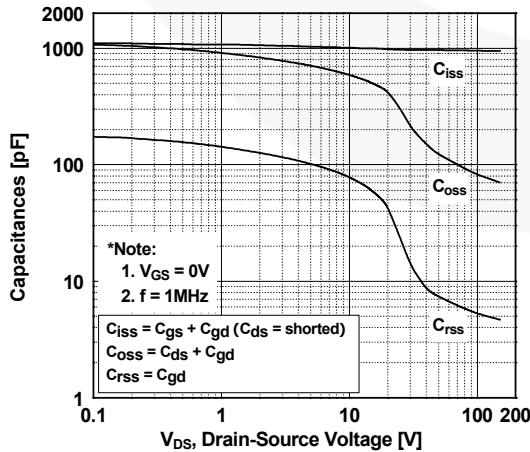


Figure 2. Transfer Characteristics

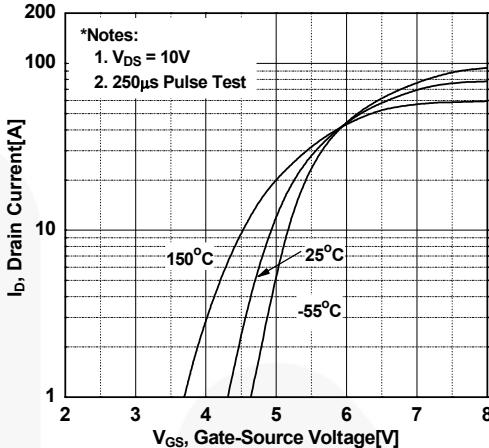


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

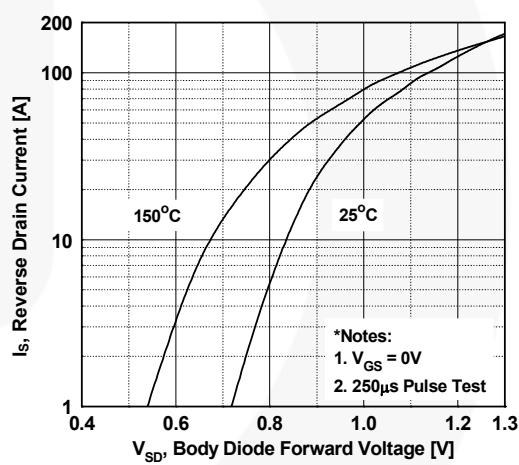
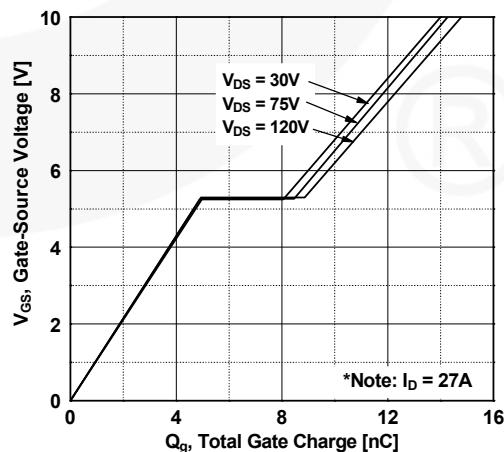


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

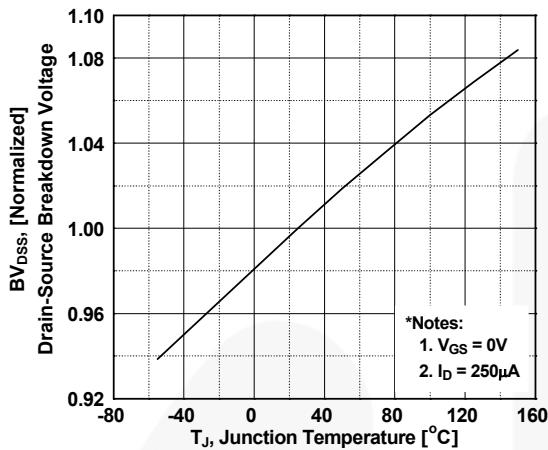


Figure 9. Maximum Safe Operating Area

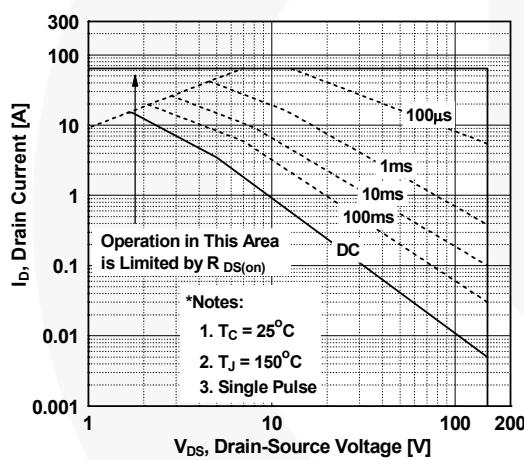


Figure 11. Eoss vs. Drain to Source Volatage

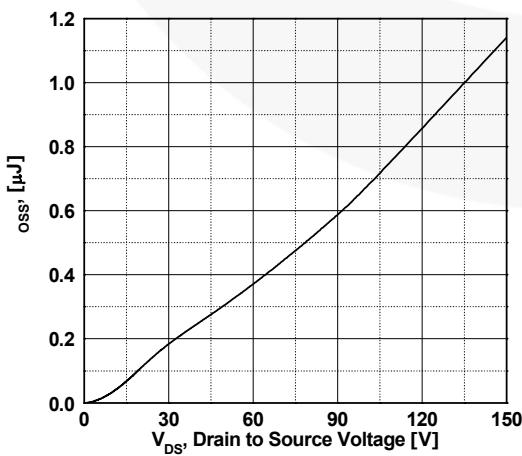


Figure 8. On-Resistance Variation vs. Temperature

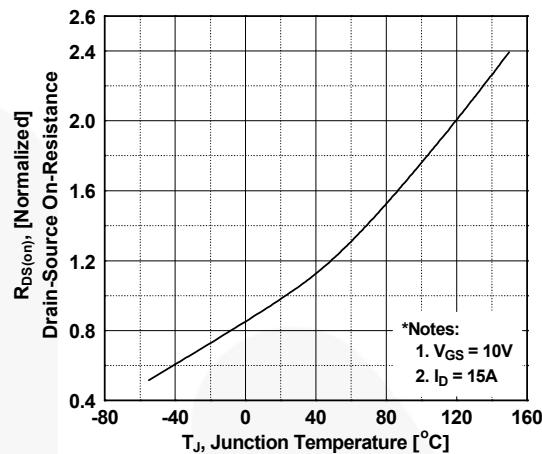


Figure 10. Maximum Drain Current vs. Case Temperature

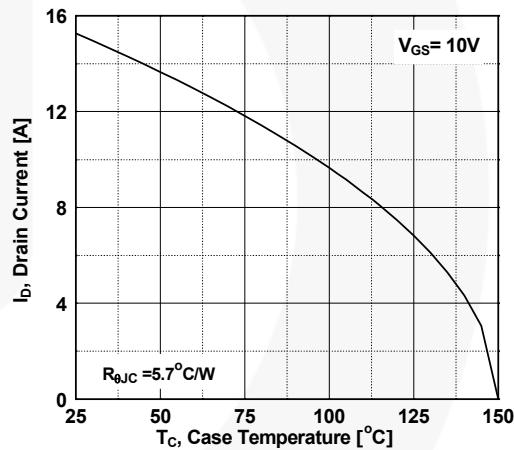
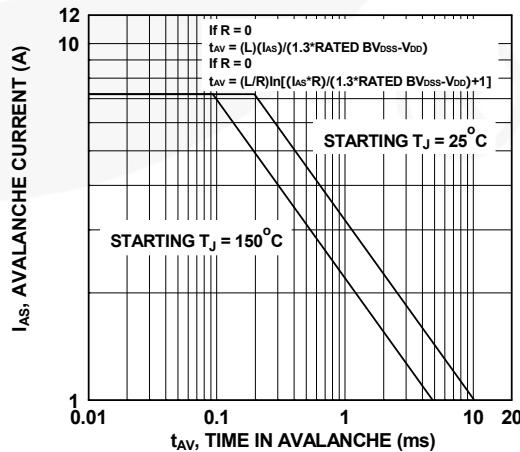
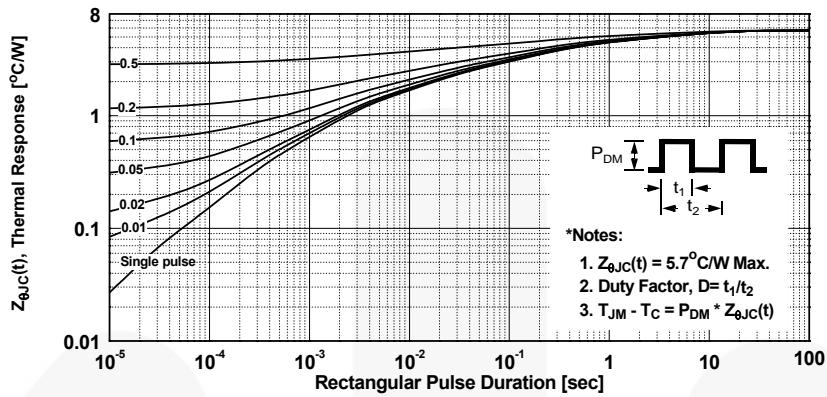


Figure 12. Unclamped Inductive Switching Capability



Typical Performance Characteristics (Continued)

Figure 13. Transient Thermal Response Curve



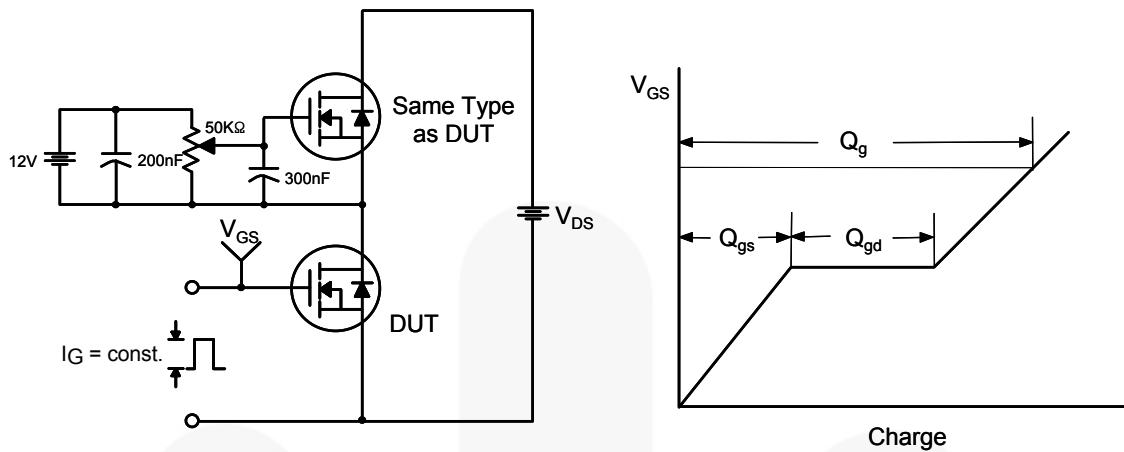


Figure 14. Gate Charge Test Circuit & Waveform

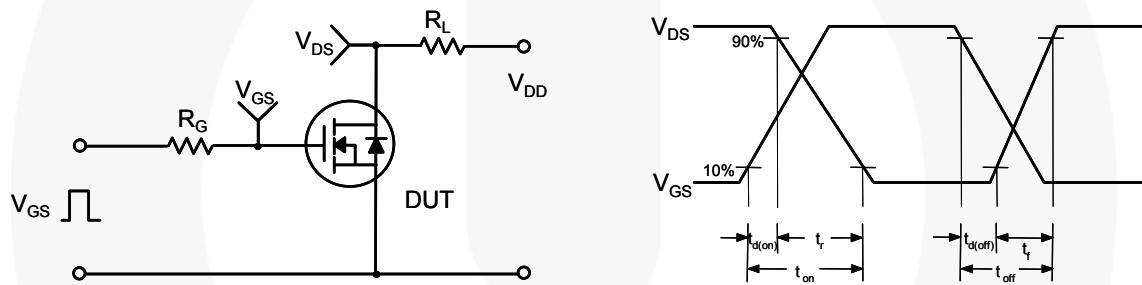


Figure 15. Resistive Switching Test Circuit & Waveforms

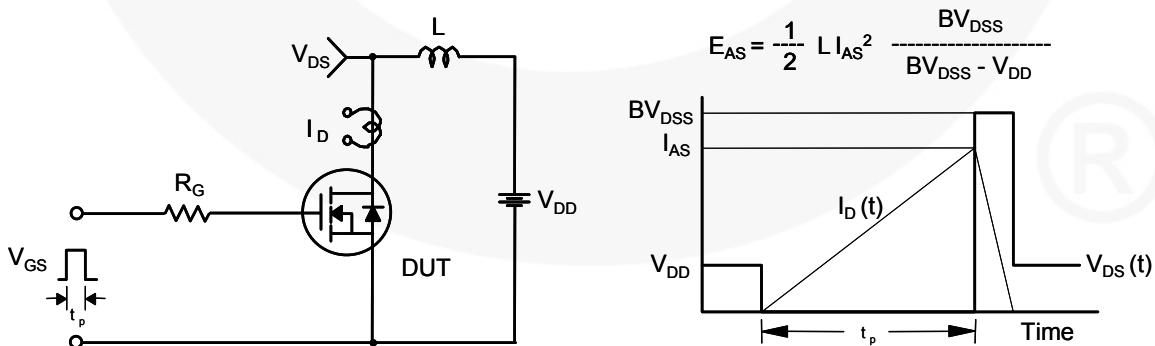


Figure 16. Unclamped Inductive Switching Test Circuit & Waveforms

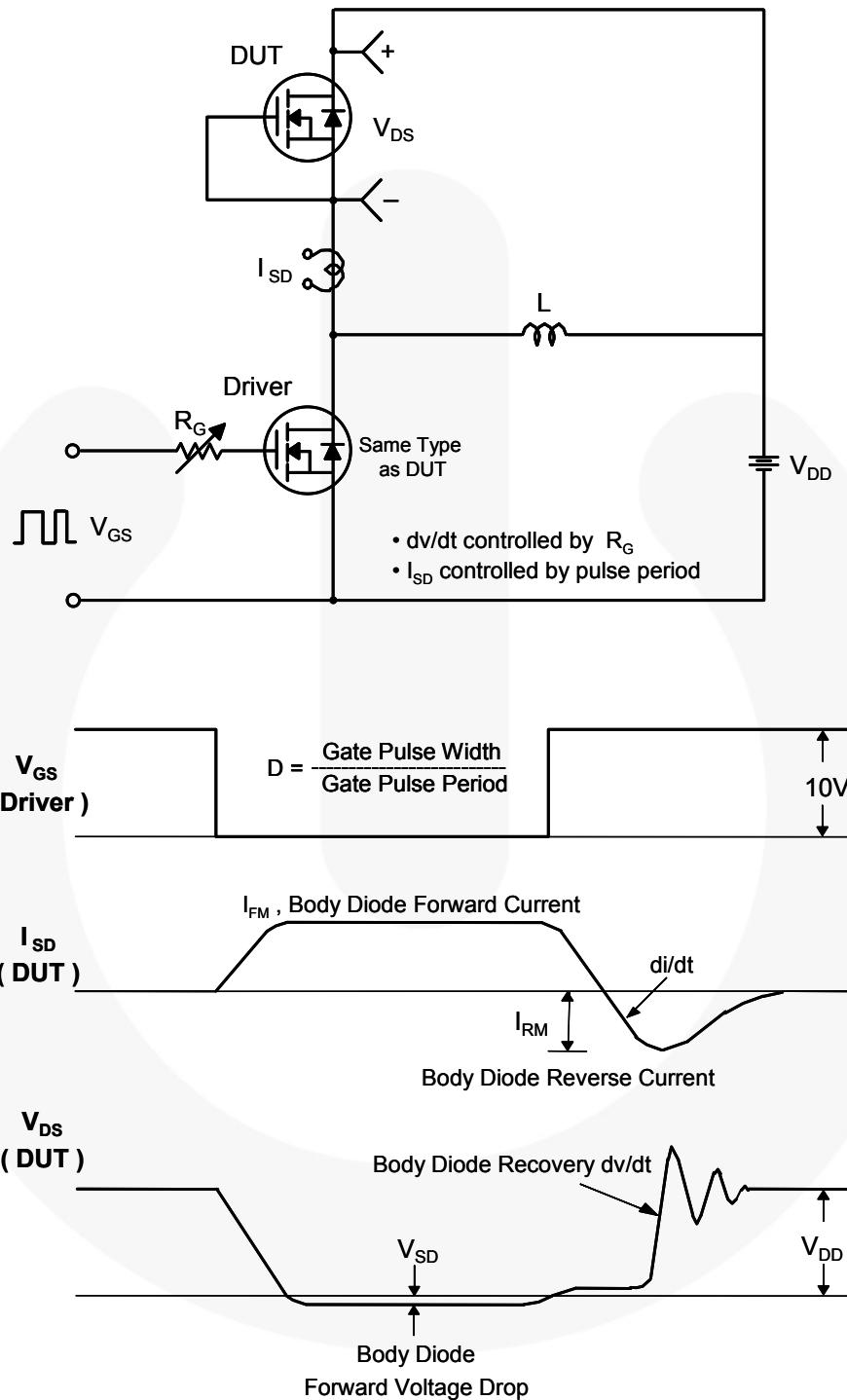
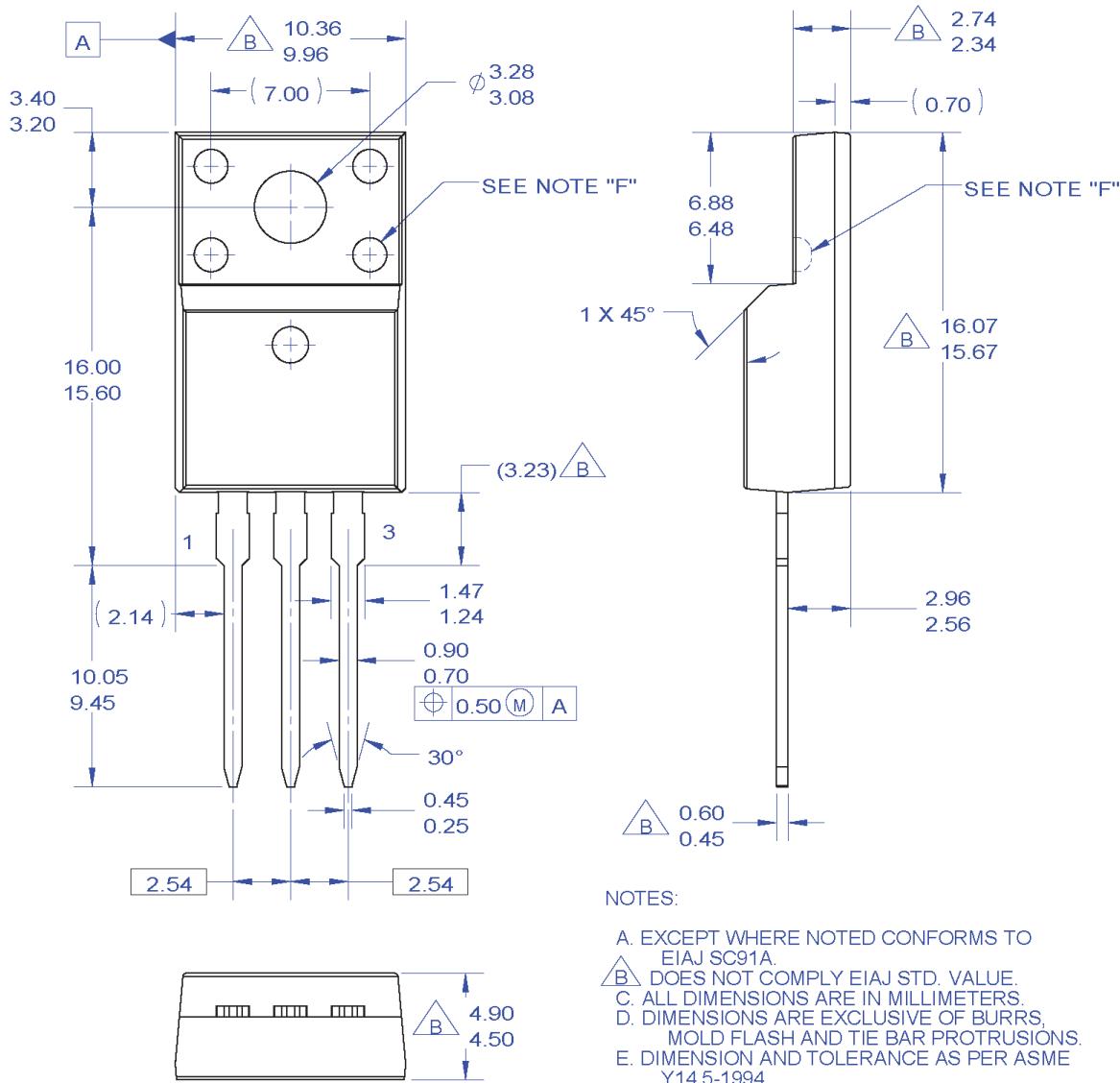


Figure 17. Peak Diode Recovery dv/dt Test Circuit & Waveforms

Mechanical Dimensions



NOTES:

- EXCEPT WHERE NOTED CONFORMS TO EIAJ SC91A.
- DOES NOT COMPLY EIAJ STD. VALUE.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- DIMENSION AND TOLERANCE AS PER ASME Y14.5-1994.
- OPTION 1 - WITH SUPPORT PIN HOLE.
OPTION 2 - NO SUPPORT PIN HOLE.
- DRAWING FILE NAME: TO220M03REV3

Figure 18. TO220, Molded, 3-Lead, Full Pack, EIAJ SC91, Straight Lead

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Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

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